L Number	Hits	Search Text	DB	Time stamp
Number 1	6	(("5213715") or ("5837119") or	USPAT;	2003/08/17
		("5624268") or ("6238599") or ("20020005247") or ("20030080768")).PN.	US-PGPUB	11:22
2	4	"1317426"	EPO; DERWENT	2003/08/17
3	4	"1317426"	JPO; DERWENT	2003/08/17
4	0	"411317426"	JPO; DERWENT	2003/08/17
5	2	"11317426"	JPO;	2003/08/17
6	7	"126428"	DERWENT JPO;	11:24 2003/08/17
7	1	"2003126428"	DERWENT JPO;	11:25
8	10957	ahn	DERWENT JPO;	11:26
9	1	ahn and acf	DERWENT JPO;	11:27 2003/08/17
10	95	ahn and adhesive	DERWENT JPO;	11:27 2003/08/17
11	748	((anisotropic with film) or acf) and	DERWENT USPAT;	11:29 2003/08/17
		((conductive or conductor or metal or gold or au) with (bead or bump))	US-PGPUB; EPO; JPO;	11:40
			DERWENT; IBM TDB	
12	5637	((anisotropic with film) or acf or adhesive) and ((conductive or conductor	USPAT; US-PGPUB;	2003/08/17 12:34
		or metal or gold or au) with (bead or bump))	EPO; JPO; DERWENT;	
13	574	(((anisotropic with film) or acf) and	IBM_TDB USPAT;	2003/08/17
		((conductive or conductor or metal or gold or au) with (bead or bump))) and	US-PGPUB; EPO; JPO;	12:53
		(@ad<20010821)	DERWENT; IBM TDB	
14	5	5965064.URPN.	USPAT	2003/08/17
15	2	("5120665"   "5225966").PN.	USPAT	2003/08/17
16	0	11317426.URPN.	USPAT	2003/08/17
17	1432	((anisotropic near film) or acf or (conductive adj adhesive)) and	USPAT; US-PGPUB;	2003/08/17
		((conductive or conductor or metal or gold or au) with (bead or bump))	EPO; JPO; DERWENT;	25015
18	781	(((anisotropic near film) or acf or	IBM_TDB USPAT;	2003/08/17
	,,,,	(conductive adj adhesive)) and (conductive or conductor or metal or	US-PGPUB; EPO; JPO;	12:36
		gold or au) with (bead or bump))) and (d(ielectric or insulation or insulating	DERWENT; IBM TDB	
19	619	or resin) with (bead or bump)) ((((anisotropic near film) or acf or	USPAT;	2003/08/17
		((conductive adj adhesive)) and ((conductive or conductor or metal or	US-PGPUB; EPO; JPO;	13:38
		gold or au) with (bead or bump))) and (d(ielectric or insulation or insulating	DERWENT; IBM TDB	
		or resin) with (bead or bump))) and (@ad<20010821)	-2	
20	431	(((((anisotropic near film) or acf or (conductive adj adhesive)) and	USPAT; US-PGPUB;	2003/08/17
		((conductive or conductor or metal or gold or au) with (bead or bump))) and	EPO; JPO; DERWENT;	
		(d(ielectric or insulation or insulating or resin) with (bead or bump))) and	IBM_TDB	
		(@ad<20010821)) not (((anisotropic with film) or acf) and ((conductive or		
		conductor or metal or gold or au) with (bead or bump))) and (@ad<20010821))		
	l	1	L	

21	302	((((((anisotropic near film) or acf or (conductive adj adhesive)) and	USPAT; US-PGPUB;	2003/08/17 12:39
		((conductive or conductor or metal or gold or au) with (bead or bump))) and	EPO; JPO; DERWENT;	
		(d(ielectric or insulation or insulating or resin) with (bead or bump))) and	IBM_TDB	
		(@ad<20010821)) not ((((anisotropic with film) or acf) and ((conductive or		
		conductor or metal or gold or au) with (bead or bump))) and (@ad<20010821))) and		
22	0	(solder or snpb or pbsn or (lead near tin)) 257/514.ccls. and ((anisotropic near	HCDAM.	2002/09/17
22		film) or acf or (conductive adj adhesive)) and ((conductive or conductor	USPAT; US-PGPUB; EPO; JPO;	2003/08/17 12:51
		or metal or gold or au) with (bead or bump))	DERWENT; IBM TDB	
23	1	1 · · · · · ·	USPAT; US-PGPUB;	2003/08/17
		adhesive))	EPO; JPO; DERWENT;	
24	3996	257/\$.ccls. and ((anisotropic near film)	IBM_TDB USPAT;	2003/08/17
		or acf or (conductive adj adhesive))	US-PGPUB; EPO; JPO;	12:53
25	117	050/514	DERWENT; IBM_TDB	
25	117	252/514.ccls. and ((anisotropic near film) or acf or (conductive adj adhesive))	USPAT; US-PGPUB;	2003/08/17
		adnesive	EPO; JPO; DERWENT; IBM TDB	
26	117	(252/514.ccls. and ((anisotropic near film) or acf or (conductive adj	USPAT; US-PGPUB;	2003/08/17
		adhesive))) and (@ad<20010821)	EPO; JPO; DERWENT;	
27	18	5180888.URPN.	IBM_TDB USPAT	2003/08/17
28	5	5586892.URPN.	USPAT	12:59 2003/08/17
29	1	6332786.URPN.	USPAT	13:10   2003/08/17   13:12
30	8	("4902857"   "5001302"   "5586892"   "5604379"   "5624268"   "5681402"	USPAT	2003/08/17 13:12
31	3	"5813870"   "6008451").PN. ("4113981"   "5001302"   "5180888").PN.	USPAT	2003/08/17
32	21	("4113981"   "4362903"   "4425263"   "4496475"   "4568592"   "4640981"	USPAT	2003/08/17 13:15
		"4642421"   "4731503"   "4737112"   "4740657"   "4832455"   "4844588"		
		"4862153"   "4868637"   "4896946"   "4902857"   "4917466"   "4964700"		
33	97	,	USPAT;	2003/08/17
		film) or acf or (conductive adj adhesive))	US-PGPUB; EPO; JPO; DERWENT;	13:35
34	40	(252/512.ccls. and ((anisotropic near	IBM_TDB USPAT;	2003/08/17
		film) or acf or (conductive adj adhesive))) not (252/514.ccls. and	US-PGPUB; EPO; JPO;	13:23
2.5	_	<pre>((anisotropic near film) or acf or (conductive adj adhesive)))</pre>	DERWENT; IBM_TDB	
35	0	252/E23.04.ccls. and ((anisotropic near film) or acf or (conductive adj	USPAT; US-PGPUB;	2003/08/17 13:36
		adhesive))	EPO; JPO; DERWENT; IBM TDB	
L				l

Page 2

36	18	· · · · · · · · · · · · · · ·	USPAT;	2003/08/17
		film) or acf or (conductive adj	US-PGPUB;	13:37
		adhesive))	EPO; JPO;	
			DERWENT;	!
27	1.0	257/752	IBM_TDB	2003/08/17
37	10	1	USPAT;	2003/08/17
		film) or acf or (conductive adj	US-PGPUB; EPO; JPO;	13:30
		adhesive))	DERWENT;	
			IBM TDB	
38	153	257/783.ccls. and ((anisotropic near	USPAT;	2003/08/17
30	133	film) or acf or (conductive adj	US-PGPUB;	13:40
		adhesive))	EPO; JPO;	13.10
			DERWENT;	<u> </u>
			IBM TDB	
39	133	(257/783.ccls. and ((anisotropic near	USPAT;	2003/08/17
		film) or acf or (conductive adj	US-PGPUB;	13:45
		adhesive))) and (@ad<20010821)	EPO; JPO;	
			DERWENT;	İ
			IBM_TDB	
40	85	((257/783.ccls. and ((anisotropic near	USPĀT;	2003/08/17
ŀ		film) or acf or (conductive adj	US-PGPUB;	13:41
		adhesive))) and (@ad<20010821)) and	EPO; JPO;	
	1	(dielectric or insulation or insulating)	DERWENT;	
			IBM_TDB	
41	116		USPAT;	2003/08/17
		film) or acf or (conductive adj	US-PGPUB;	13:40
		adhesive))	EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
42	106		USPAT;	2003/08/17
		film) or acf or (conductive adj	US-PGPUB;	13:41
		adhesive))) and (@ad<20010821)	EPO; JPO; DERWENT;	
ļ				
43	59	((438/119.ccls. and ((anisotropic near	IBM_TDB USPAT;	2003/08/17
43	, , ,	film) or acf or (conductive adj	US-PGPUB;	13:45
		adhesive))) and (@ad<20010821)) and	EPO; JPO;	15.45
		(dielectric or insulation or insulating)	DERWENT;	
		(dicieotife of insulation of insulating)	IBM TDB	
44	954	(((anisotropic near film) or acf or	USPAT;	2003/08/17
		(conductive adj adhesive)) and	US-PGPUB;	13:46
ļ		((conductive or conductor or metal or	EPO; JPO;	
		gold or au) with (bead or bump))) and	DERWENT;	
		(dielectric or insulation or insulating)	IBM TDB	
45	745	((((anisotropic near film) or acf or	USPAT;	2003/08/17
-		(conductive adj adhesive)) and	US-PGPUB;	13:46
		((conductive or conductor or metal or	EPO; JPO;	
		gold or au) with (bead or bump))) and	DERWENT;	
1		(dielectric or insulation or insulating))	IBM_TDB	1
1,5		and (@ad<20010821)		0000 (00 (7.7
46	2412	((anisotropic near film) or underfill or	USPAT;	2003/08/17
		encapsulant or encapsulate or acf or	US-PGPUB;	13:47
		(conductive adj adhesive)) and	EPO; JPO;	
		((conductive or conductor or metal or	DERWENT;	
47	1535	gold or au) with (bead or bump)) (((anisotropic near film) or underfill or	IBM_TDB USPAT;	2003/08/17
1 1	] 1000	encapsulant or encapsulate or acf or	US-PGPUB;	13:46
		(conductive adj adhesive)) and	EPO; JPO;	10.10
]		((conductive adj admessive)) and ((conductive or conductor or metal or	DERWENT;	
1		gold or au) with (bead or bump))) and	IBM TDB	
		(dielectric or insulation or insulating)		
49	870	(((((anisotropic near film) or underfill	USPAT;	2003/08/17
[		or encapsulant or encapsulate or acf or	US-PGPUB;	13:48
	]	(conductive adj adhesive)) and	EPO; JPO;	
]	ļ İ	((conductive or conductor or metal or	DERWENT;	
		gold or au) with (bead or bump))) and	IBM_TDB	
		(dielectric or insulation or insulating))	-	
		and (@ad<20010821)) and ((dielectric or		
		insulation or insulating) with		
		(conductive or conductor or motal or cold		i e
ļ		<pre>(conductive or conductor or metal or gold   or au))</pre>		

48	1187	((((anisotropic near film) or underfill	USPAT;	2003/08/17
		or encapsulant or encapsulate or acf or	US-PGPUB;	13:49
		(conductive adj adhesive)) and	EPO; JPO;	
1		((conductive or conductor or metal or	DERWENT;	1
ì	1	gold or au) with (bead or bump))) and	IBM_TDB	
1	j	(dielectric or insulation or insulating))	i	1
		and (@ad<20010821)		1